




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8S207S6T3C STM8S207S6T3CTR	S34Y*765XXXV	A	998Z	2018-06-09
	Amount	UoM	Unit type	ST ECOPACK Grade
	372.01	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10X10X1.4	44	L Bend	
Comment	Package : 4Y LQFP 44 10x10x1.4 1.0 0076922			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	S34Y*765XXV				5999999.0	999997.6
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.464	mg	supplier	die	Silicon (Si)	7440-21-3		6.258	mg	968131	16822
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	2785	48
				supplier	metallization	Copper (Cu)	7440-50-8		0.060	mg	9282	161
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.007	mg	1083	19
				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	1392	24
				supplier	Passivation	Silicon Nitride	12033-89-5		0.016	mg	2475	43
				supplier	Passivation	Silicon Oxide	7631-86-9		0.096	mg	14851	258
Die Attach Epoxy_ABLEBOND 3230_H	M-011 Other inorganic materials	0.879	mg	Supplier	Metals	Silver	7440-22-4		0.792	mg	901000	2130
				Supplier	Organic Compound	Highly cross-linked polymer	Proprietary		0.087	mg	99000	234
EMC_G631SHQ_Sumitomo	M-011 Other inorganic materials	248.479	mg	Supplier	Organic Compound	Epoxy Resin A	Proprietary		5.218	mg	21000	14027
				Supplier	Organic Compound	Epoxy Resin B	Proprietary		5.218	mg	21000	14027
				Supplier	Organic Compound	Phenol Resin	Proprietary		13.915	mg	56000	37405
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		193.925	mg	780450	521294
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		28.655	mg	115320	77027
				Supplier	Additives	Carbon Black	1333-86-4		1.548	mg	6230	4161
BondingWire_Ag_MKE	Bonding Wire	0.459	mg	Supplier	Metals	Silver	7440-22-4		0.441	mg	960000	1184
				Supplier	Metals	Others	Proprietary		0.018	mg	40000	49
				Supplier	Metals	Tin	7440-31-5		2.696	mg	1000000	7247
Anode Ball_Tin_Asahi	Metals	2.696	mg	Supplier	Metals	Tin	7440-31-5		2.696	mg	1000000	7247
Leadframe_C9+Ag_MITSUI	Metals	113.030	mg	Supplier	Metals	Copper	7440-50-8		109.888	mg	972200	295391
				Supplier	Metals	Iron	7439-89-6		2.588	mg	22900	6958
				Supplier	Metals	Zinc	7440-66-6		0.170	mg	1500	456
				Supplier	Non-metals	Phosphorus	7723-14-0		0.034	mg	300	91
				Supplier	Metals	Silver	7440-22-4		0.350	mg	3100	942